

# 1A, 50V - 1000V High Efficient Surface Mount Rectifier

#### **FEATURES**

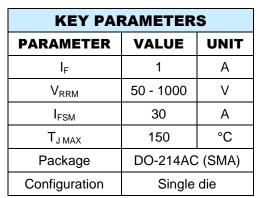
- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- Lighting application
- Snubber
- Freewheeling application

#### **MECHANICAL DATA**

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.060g (approximately)







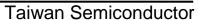




DO-214AC (SMA)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					1					
PARAMETER	SYMBOL	HS1A	HS1B	HS1D	HS1F	HS1G	HS1J	HS1K	HS1M	UNIT
Marking code on the device		HS1A	HS1B	HS1D	HS1F	HS1G	HS1J	HS1K	HS1M	
Repetitive peak reverse voltage	$V_{RRM}$	50	100	200	300	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	35	70	140	210	280	420	560	700	V
Forward current	I <sub>F</sub>				•	1				Α
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	30				А				
Junction temperature	T <sub>J</sub>	T <sub>J</sub> - 55 to +150			°C					
Storage temperature	T <sub>STG</sub>	- 55 to +150			°C					





THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	70	°C/W		

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
(1)	HS1A HS1B HS1D HS1F		.,	-	1.0	V
Forward voltage <sup>(1)</sup>	HS1G		V <sub>F</sub>	-	1.3	V
	HS1J HS1K HS1M			-	1.7	V
		T <sub>J</sub> = 25°C		-	5	μA
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		T <sub>J</sub> = 100°C	I <sub>R</sub>	-	50	μΑ
		T <sub>J</sub> = 125°C		-	150	μΑ
Junction capacitance	HS1A HS1B HS1D HS1F HS1G	1MHz, V <sub>R</sub> = 4.0V	CJ	20	-	pF
	HS1J HS1K HS1M			15	-	pF
Reverse recovery time	HS1A HS1B HS1D HS1F HS1G	I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1.0A, I <sub>rr</sub> = 0.25A	t <sub>rr</sub>	-	50	ns
	HS1J HS1K HS1M			-	75	ns

#### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
HS1x	DO-214AC (SMA)	7,500 / Tape & Reel		

### Notes:

1. "x" defines voltage from 50V(HS1A) to 1000V(HS1M)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve

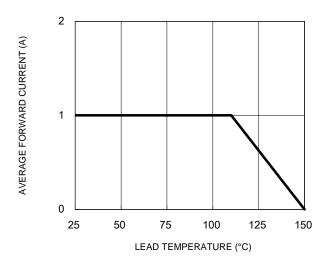


Fig.3 Typical Reverse Characteristics

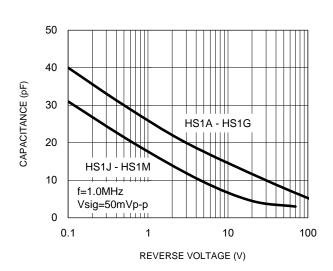
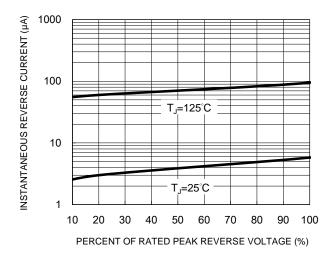


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



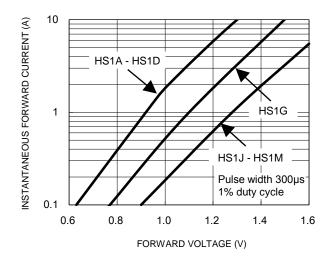
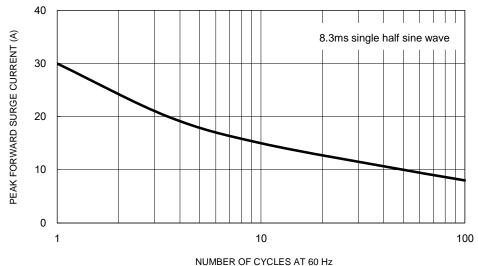


Fig.5 Maximum Non-Repetitive Forward Surge Current



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Version: L2102

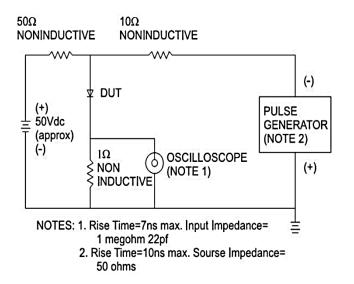


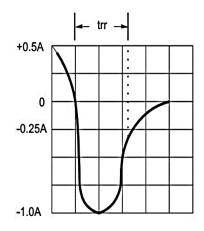


#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram



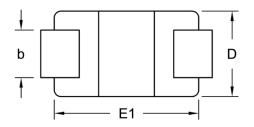


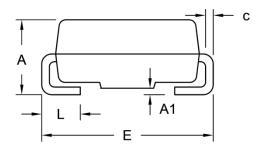




#### **PACKAGE OUTLINE DIMENSIONS**

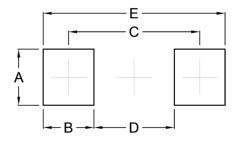
### DO-214AC (SMA)





DIM. Unit		(mm) Unit (i		inch)	
Dilvi.	Min.	Max.	Min.	Max.	
Α	1.99	2.50	0.078	0.098	
A1	0.10	0.20	0.004	0.008	
b	1.27	1.58	0.050	0.062	
С	0.15	0.31	0.006	0.012	
D	2.29	2.83	0.090	0.111	
E	4.95	5.33	0.195	0.210	
E1	4.06	4.60	0.160	0.181	
L	0.90	1.41	0.035	0.056	

#### **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.68	0.066
В	1.52	0.060
С	3.93	0.155
D	2.41	0.095
E	5.45	0.215

### **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

= Date Code ΥW F = Factory Code

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